Vishay Siliconix

N-Channel 40 V (D-S) MOSFET



PRODUCT SUMMARY				
V _{DS} (V)	40			
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.0022			
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 4.5 \text{ V}$	0.0032			
Q _g typ. (nC)	21.5			
I _D (A) ^a	128			
Configuration	Single			

FEATURES

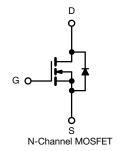
- TrenchFET® Gen IV power MOSFET
- 40 V drain-source break-down voltage
- Tuned for low Qq and Qoss
- 100 % R_a and UIS tested

 Material categorization: for definitions of compliance please see www.vishav.com/doc?99912



APPLICATIONS

- Synchronous rectification
- High power density DC/DC
- Motor drive control



ORDERING INFORMATION	
Package	PowerPAK SO-8
Lead (Pb)-free and halogen-free	SIRA54ADP-T1-RE3

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	40	V	
Gate-source voltage		V _{GS}	+20, -16	v	
Continuous drain current (T _J = 150 °C)	T _C = 25 °C		128		
	T _C = 70 °C		103		
	T _A = 25 °C	I _D	36.2 b, c		
	T _A = 70 °C		29 b, c	^	
Pulsed drain current (t = 100 μs)		I _{DM}	300	Α Α	
Continuous source-drain diode current	T _C = 25 °C		59.7		
	T _A = 25 °C	I _S	4.7 b, c		
Single pulse avalanche current	L = 0.1 mH	I _{AS}	25		
Single pulse avalanche Energy	L = 0.1 IIII	E _{AS}	31.25	mJ	
Maximum power dissipation	T _C = 25 °C		65.7		
	T _C = 70 °C	ь	425	□ w	
	T _A = 25 °C	P _D	5.2 ^{b, c}	VV	
	T _A = 70 °C		3.3 b, c		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) d, e		Ĭ.	260		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient b, f	t ≤ 10 s	R _{thJA}	20	24	°C/W	
Maximum junction-to-case (drain)	Steady state	R_{thJC}	1.5	1.9	- C/VV	

Notes

- a. Based on $T_C = 25 \, ^{\circ}C$
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 10 s
- d. See solder profile (<u>www.vishay.com/doc?73257</u>). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- f. Maximum under steady state conditions is 62.5 °C/W



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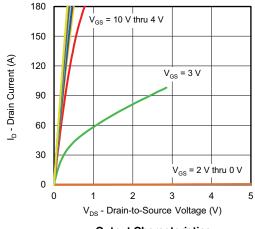
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static					•	•	
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_{D} = 1 \text{ mA}$	40	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I _D = 1 mA	-	25	-	14/00	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-5.2	-	mV/°C	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1	-	2.5	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = +20, -16 \text{ V}$	-	-	± 100	nA	
Zero gate voltage drain current		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1	μΑ	
	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V, T _J = 75 °C	-	-	20		
	_	$V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}$	-	0.0018	0.0022		
Drain-source on-state resistance a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 15 A	-	0.0024	0.0032	Ω	
Forward transconductance a	9 _{fs}	V _{DS} = 10 V, I _D = 15 A	-	98	-	S	
Dynamic ^b	1 9.2				1	I	
Input capacitance	C _{iss}		-	3850	_	pF	
Output capacitance	Coss	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	655	-		
Reverse transfer capacitance	C _{rss}		-	75	-		
	1.22	V _{DS} = 20 V, V _{GS} = 10 V, I _D = 10 A	-	46.7	70	nC	
Total gate charge	Qg	V _{DS} = 20 V, V _{GS} = 4.5 V, I _D = 10 A	-	21.5	32		
Gate-source charge	Q _{gs}		_	9.3	-		
Gate-drain charge	Q_{gd}		-	4	-		
Output charge	Q _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	-	24.5	-		
Gate resistance	R _q	f = 1 MHz	0.5	1.1	1.8	Ω	
Turn-on delay time	t _{d(on)}		-	15	30		
Rise time	t _r	$V_{DD} = 20 \text{ V}, R_L = 2 \Omega$	-	6	12		
Turn-off delay time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	30	60		
Fall time	t _f		-	6	12		
Turn-on delay time	t _{d(on)}		-	26	52	ns	
Rise time	t _r	$V_{DD} = 20 \text{ V}, R_{I} = 2 \Omega$	-	63	126		
Turn-off delay time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$	-	33	66		
Fall time	t _f		-	10	20		
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	Is	T _C = 25 °C	-	-	59.7		
Pulse diode forward current ($t_p = 100 \mu s$)	I _{SM}		-	-	300	A	
Body diode voltage	V _{SD}	I _S = 5 A	-	0.72	1.1	V	
Body diode reverse recovery time	t _{rr}		-	29	58	ns	
Body diode reverse recovery charge	Q _{rr}	$I_F = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	23	46	nC	
Reverse recovery fall time	t _a	$T_J = 25 ^{\circ}\text{C}$	-	15	-	ns	
Reverse recovery rise time	t _b		-	14	-		

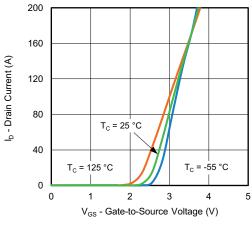
Notes

- g. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- h. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

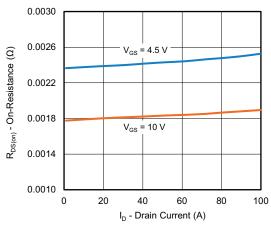


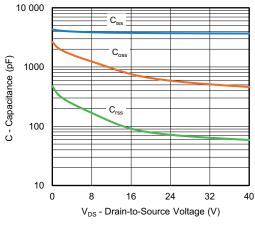






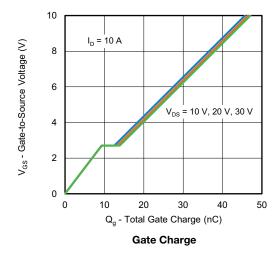


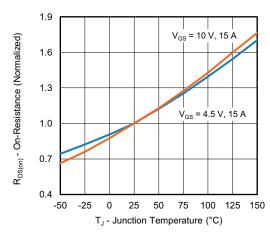




On-Resistance vs. Drain Current

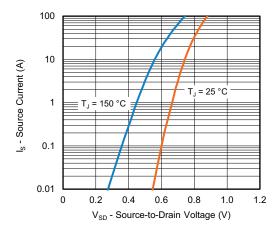
Capacitance



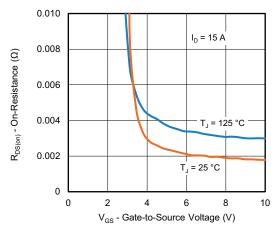


On-Resistance vs. Junction Temperature

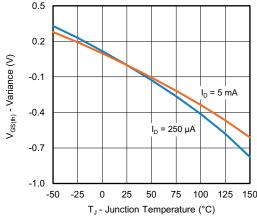




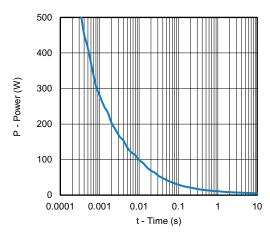
Source-Drain Diode Forward Voltage



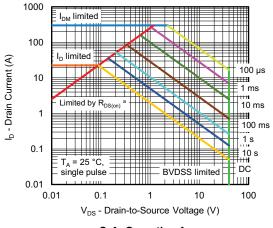
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient

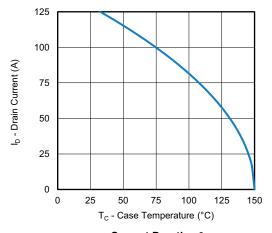


Safe Operating Area

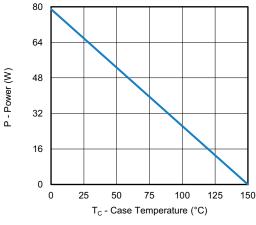
Note

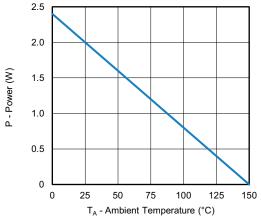
a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified











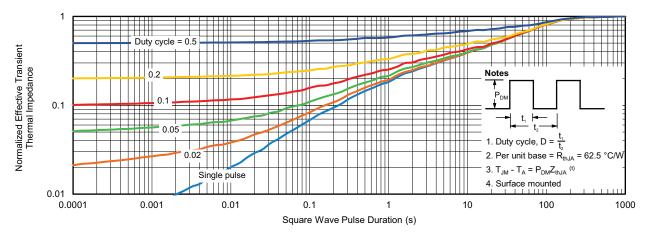
Power, Junction-to-Case

Power, Junction-to-Ambient

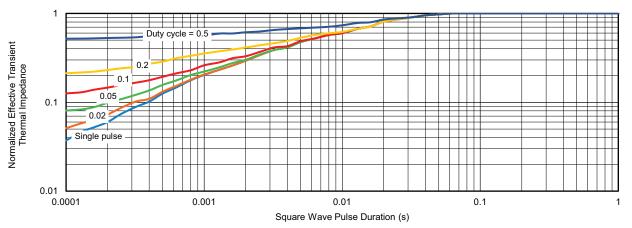
Note

b. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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